ABSTRACT

The present disclosure relates to the technical field of semiconductors, and provides a package substrate and a semiconductor structure with the package substrate. The package substrate includes a body (10) and a conductive layer (20). The body (10) includes an opening region (11). The conductive layer (20) is disposed at the opening region (11). The conductive layer (20) includes a first conductive bridge (21) and a second conductive bridge (22). The first conductive bridge (21) and the second conductive bridge (22) are disposed at intervals. The first conductive bridge (21) is provided with at least one first via (211). The first conductive bridge (21) and the second conductive bridge (22) are disposed at intervals in the opening region (11), ~~so that signal transmission quality of the conductive layer can be enhanced, and the distortion resistance ability of the body can be increased by controlling the widths of the first conductive bridge and the second conductive bridge. The overall area of the conductive layer can be reduced by providing the at least one first via on the first conductive bridge, thereby reducing warpage problem of the body and improving service performance of the package substrate structurally~~.

Fig. 1